

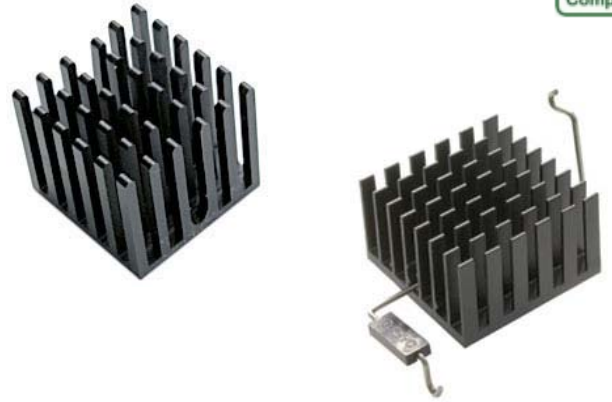


BOARD LEVEL COOLING - 3745

3745 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
374524B00032G	BGA, FPGA
374524B60023G	BGA, FPGA



HEAT SINK DETAILS

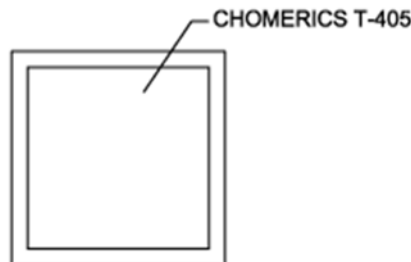
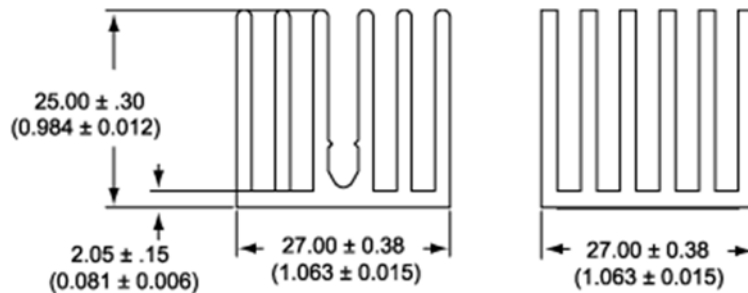
Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options: 374524B00032G	Tape
Device Attachment Options: 374524B60023G	Solder Anchor Clip
Thermal Interface Material: 374524B00032G	T405R Chomerics Tape for Metal surfaces
Thermal Interface Material: 374524B60023G	T766 Chomerics Phase Change for All Surfaces

Property	Details
Heat Sink Width (mm)	27.00
Heat Sink Length (mm)	27.00
Heat Sink Height (mm)	25.00
Heat Sink Mounting Direction	Horizontal, Vertical

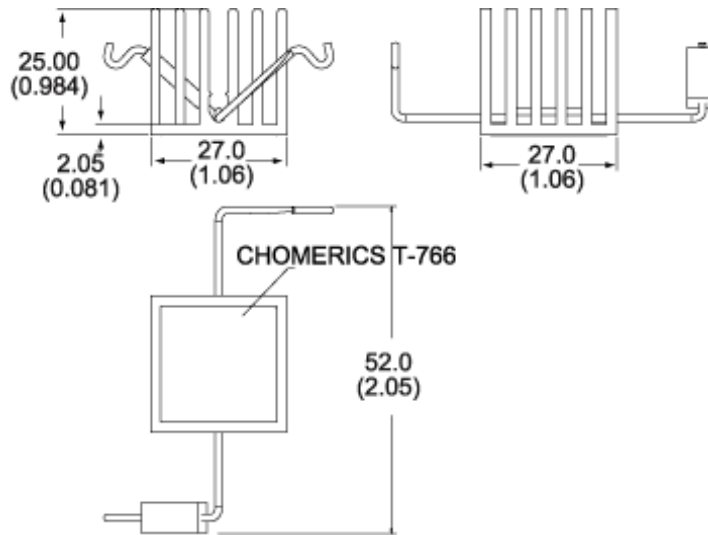
MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

Part Number: 374524B00032G



Part Number: 374524B60023G



Mounting Details:

